

Patent claims

1. An electronic device (1)
 - with a base plate (2),
 - with an electronics housing (3) which is connected to the base plate (2), with at least one bond contact bearer (5),
characterised in that the bond contact bearer (5) is supported on the base plate (2) by a supporting body (6) in such a manner that the supporting body (6) exerts a pretension force onto the bond contact bearer (5).
2. An electronic device according to claim 1, **characterised in that** a projection of the supporting body (6) above the base plate (2) is greater than the distance between the bond contact bearer (5) and the base plate (2).
3. An electronic device according to claim 1 or 2, **characterised in that** the supporting body (6) represents a separate component from the base plate (2), which is mechanically connected to the electronics housing (3).
4. An electronic device according to any one of claims 1 to 3, **characterised in that** the supporting body (6) is designed as a projecting ring or as a plurality of projecting individual segments.
5. A procedure for bonding an electronic device (1) with the following procedural stages:
 - provision of a base plate (2),
 - connection of an electronics housing (3) via a supporting body (6) with the base plate (2) in such a manner that the supporting body (6) exerts a pretension force onto the bond contact bearer (5),
 - creation of a bond connection between the bond contact bearer (5) of the electronics housing (3) and an additional bond contact bearer.